## Liu Lu

## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/8057162/publications.pdf

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|          | 2258059        |              | 2053705        |  |
|----------|----------------|--------------|----------------|--|
| 5        | 30             | 3            | 5              |  |
| papers   | citations      | h-index      | g-index        |  |
|          |                |              |                |  |
|          |                |              |                |  |
|          |                |              |                |  |
| 5        | 5              | 5            | 16             |  |
| all docs | docs citations | times ranked | citing authors |  |
|          |                |              |                |  |

| # | Article   | IF  | CITATIONS |
|---|---|-----|-----------|
| 1 | Three-dimensional interface and property of SnPb solder joint under extreme thermal shocking. Science and Technology of Welding and Joining, 2022, 27, 186-196.   | 3.1 | 12        |
| 2 | Mechanical Property of Sn-58Bi Solder Paste Strengthened by Resin. Applied Sciences (Switzerland), 2018, 8, 2024.   | 2.5 | 8         |
| 3 | Study on the Reliability of Sn–Bi Composite Solder Pastes with Thermosetting Epoxy under Thermal Cycling and Humidity Treatment. Crystals, 2021, 11, 733.   | 2.2 | 6         |
| 4 | Influence of 0.05 wt% Pr addition on interfacial microstructure and mechanical properties of Sn–0.3Ag–0.7Cu/Cu solder joint during thermal shocking. Journal of Materials Science: Materials in Electronics, 2022, 33, 7099-7108. | 2.2 | 2         |
| 5 | Board Level Drop Test for Evaluating the Reliability of High-Strength Sn–Bi Composite Solder Pastes<br>with Thermosetting Epoxy. Crystals, 2022, 12, 924.   | 2.2 | 2         |